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Kingbright WP3VGYW

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T-1(3mm) BI-COLOR INDICATOR LAMP

Part Number: WP3VGYW

Green Yellow

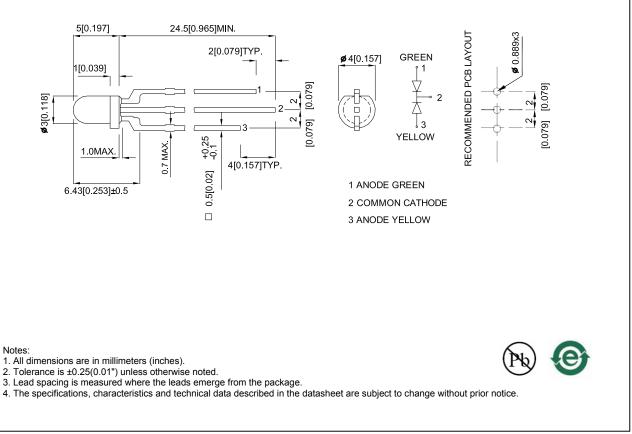
Features

- Uniform light output.
- Low power consumption.
- 3 leads with one common lead.
- Long life solid state reliability.
- RoHS compliant.

Descriptions

- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.
- The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions





Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP3VGYW	Green (GaP)	White Diffused	15	40	60°
	Yellow (GaAsP/GaP)		10	15	

Notes:

1. θ 1 / 2 is the angle from optical centerline where the luminous intensity is 1 / 2 of the optical peak value. 2. Luminous intensity / luminous Flux: + / -15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green Yellow	565 590		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green Yellow	568 588		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green Yellow	30 35		nm	IF=20mA
С	Capacitance	Green Yellow	15 20		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Green Yellow	2.2 2.1	2.5 2.5	V	I⊧=20mA
lr	Reverse Current	Green Yellow		10 10	uA	VR = 5V

Notes:

1. Wavelength: + / -1nm.

2. Forward Voltage: + / -0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

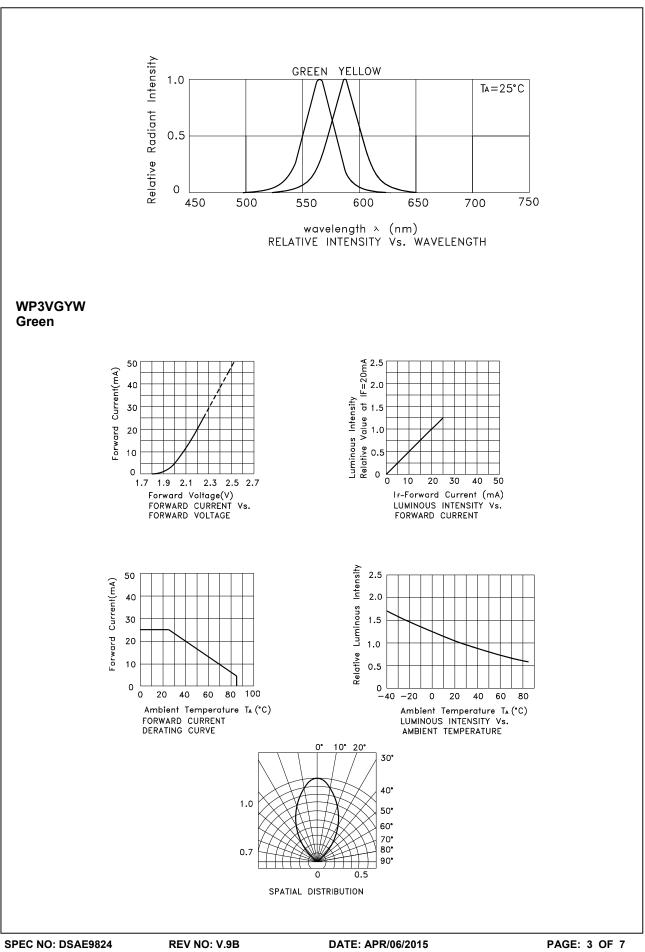
Absolute Maximum Ratings at TA=25°C

Parameter	Green	Yellow	Units		
Power dissipation	62.5	75	mW		
DC Forward Current	25	30	mA		
Peak Forward Current [1]	140	140	mA		
Reverse Voltage		V			
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				
Notes: 1. 1 / 10 Duty Cycle, 0.1ms Pulse Width.					

2. 2mm below package base.

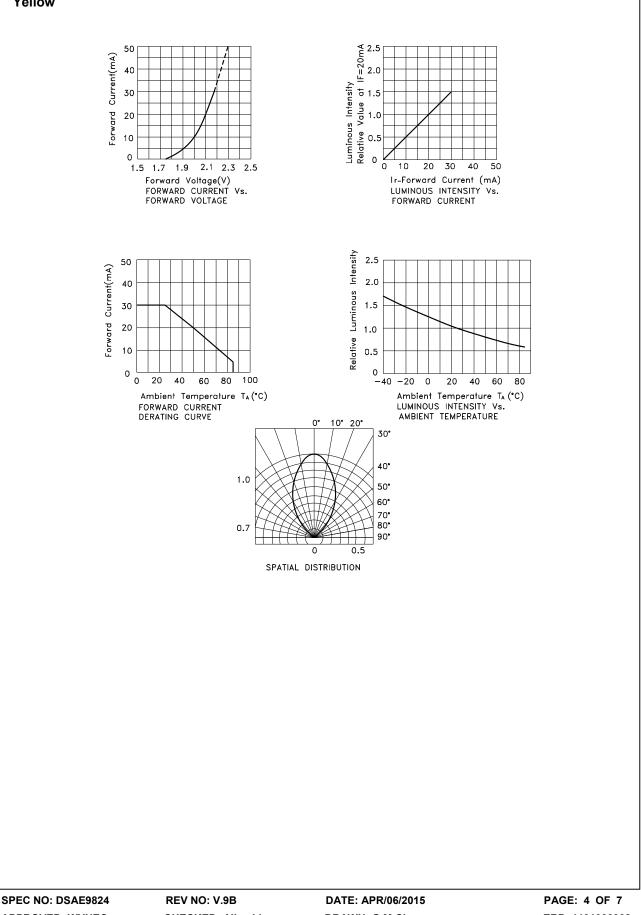
3. 5mm below package base.



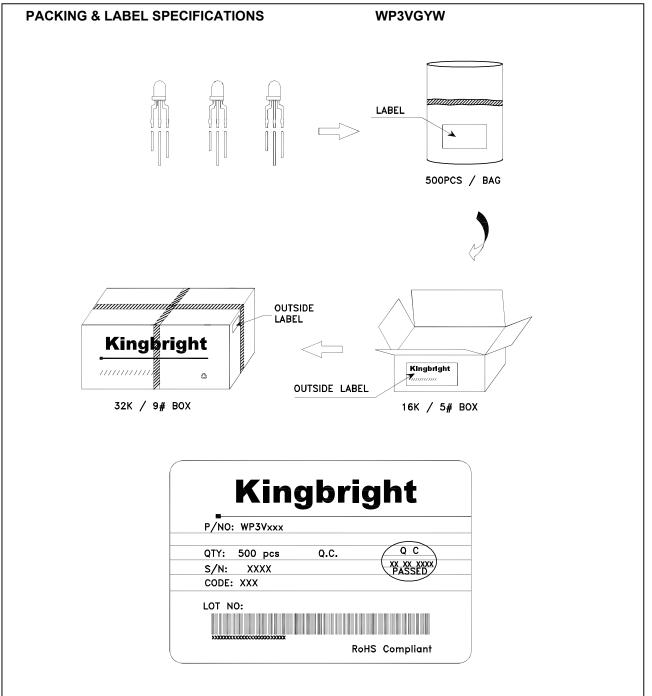




Yellow







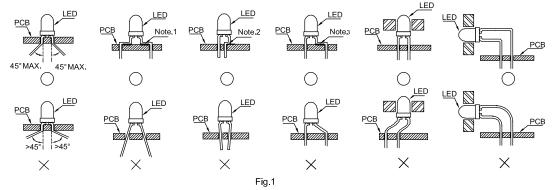
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PRECAUTIONS

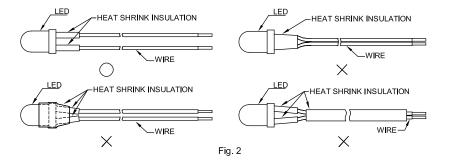
- 1. Storage conditions:
 - a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
 - b.LEDs should be stored with temperature $\leq 30^{\circ}$ C and relative humidity < 60%.
 - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



)" Correct mounting method " imes" Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure. (Fig. 2)



4. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



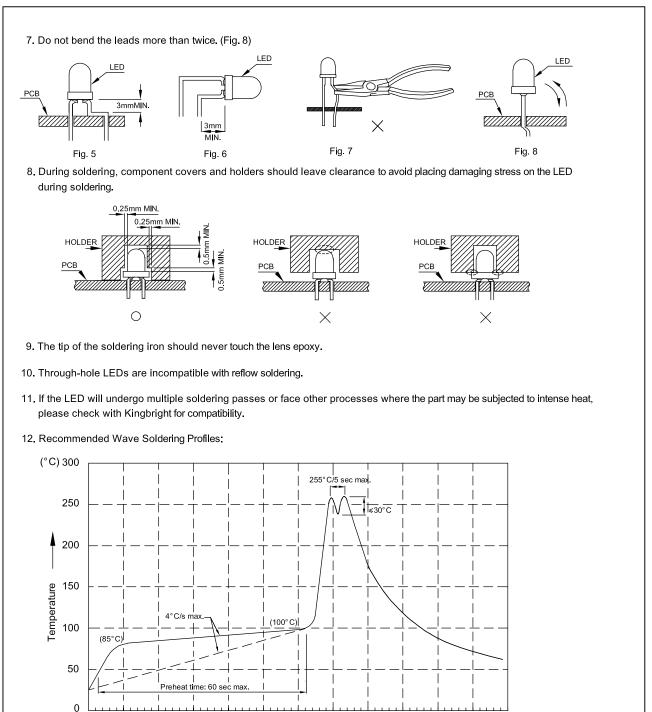
5. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)

6. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

ED

PCE





Notes:

1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C

Time(sec)

2.Peak wave soldering temperature between 245° C \sim 255° C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above $85^\circ\mbox{C}.$

4. Fixtures should not incur stress on the component when mounting and during soldering process.

5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.